



| Substrate | | | |
|-------------------------------|--|--------------|----------------|
| Product | 1 to 12 Layers Printed Circuit Board | | |
| Copper Thickness | Outer Layer : | 1/2 to 12 oz | |
| | Inner Layer : | 1/2 to 10 oz | |
| Base Materials | Aluminium, CEM-1, CEM-3, FR-4 (CTI 175 to 600) and High Tg FR-4, Automotive FR-4 | | |
| Board Thickness | Double Side Board | 0.2 ~ 3.0 mm | (8 ~ 118 mils) |
| | Four Layer Broad | 0.6 ~ 2.4 mm | (24 ~ 94 mils) |
| | Six and Eight Layer Broad | 1.0 ~ 2.4 mm | (40 ~ 94 mils) |
| | 10-Layer Board | 1.6mm | (63 mils) |
| Mimumum Inner Board Thickness | | 0.1 mm | (4 mils) |

| Circuitry | | | |
|------------------------------------|--|--------------------------|----------------|
| Minimum Drilling Hole Diameter | | 0.1 mm | (4 mils) |
| Maximum Drilling Hole Diameter | | 6.4 mm | (0.25 inch) |
| Minimum Plate Though Hole Diameter | | 0.125 mm | (5 mils) |
| | | Tolerance : +/- 0.076 mm | (+/- 0.3 mils) |
| Minimum Slot Hole Diameter | | 0.5 mm | (20 mils) |
| Drilling Tolerance | | + 0 mm | (+ 0 mils) |
| | | - 0.05 mm | (- 0.2 mils) |
| Drilling Position Deviation | | +/- 0.076 mm | (+/- 0.3 mils) |

| | | 1/2 oz | 1 oz | 2 oz |
|--------------------------|---------------------------|-----------------------------|-----------------------------|-----------------------------|
| Inner Layer Circuitry | Minimum Annular Width | 0.127 mm <i>(5 mils)</i> | 0.152 mm <i>(6 mils)</i> | 0.178 mm <i>(7 mils)</i> |
| | Minimum Circuitry Width | 0.1 mm <i>(4 mils)</i> | 0.1 mm <i>(4 mils)</i> | 0.15 mm <i>(6 mils)</i> |
| | Minimum Circuitry Spacing | 0.1 mm <i>(4 mils)</i> | 0.1 mm <i>(4 mils)</i> | 0.15 mm <i>(6 mils)</i> |
| Outer Layer Circuitry | | 1/2 oz | 1 oz | 2 oz |
| | Minimum Annular Width | 0.1 mm <i>(4 mils)</i> | 0.1 mm <i>(4 mils)</i> | 0.15 mm <i>(6 mils)</i> |
| | Minimum Circuitry Width | 0.1 mm <i>(4 mils)</i> | 0.1 mm <i>(4 mils)</i> | 0.15 mm <i>(6 mils)</i> |
| | Minimum Circuitry Spacing | 0.1 mm <i>(4 mils)</i> | 0.1 mm <i>(4 mils)</i> | 0.15 mm <i>(6 mils)</i> |
| Maximum Aspect Ratio | | 10 : 1 | | |

| Surface Finishing |
|--|
| Electrolytic Gold |
| Carbon Ink |
| Lead-free Hot Air Levelling |
| Immersion Silver |
| Immersion Tin |
| Immersion Gold |
| Hard Gold Plating |
| Organic Solderability Preservation (OSP) / Rosin |

| Solder Mask / Legend | | |
|----------------------|-----------------------|---|
| Solder Mask | Type of Solder Mask | Photo Imageable |
| | | Skillscreen |
| | Colour of Solder Mask | Magenta, Green, Blue, White, Black and Matt Green |
| | Minimum Solder Mask | Photo Imageable : 0.1 mm <i>(4 mils)</i> |

| | | | | |
|--------|--------------------------------------|-------------------------|--------------|----------------|
| | Bridge | Skillscreen : | 0.2 mm | (8 mils) |
| | Minimum PAD Size | Photo Imageable : | 0.1 mm | (4 mils) |
| | | Skillscreen : | 0.2 mm | (8 mils) |
| Legend | Colour of Legend | White, Black and Yellow | | |
| | Minimum Line Width and Spacing | | 0.15 mm | (6 mils) |
| | Minimum Legend Word Height and Width | | 0.8 x 0.8 mm | (32 x 32 mils) |

| Outline | | | | |
|--------------------------------|--|--|--------------|--------------------|
| Maximum Routing Size | | | 400 x 500 mm | (15.7 x 19.6 inch) |
| Maximum Punching Size | | | 550 x 280 mm | (9.8 x 14.9 inch) |
| Minimum Punching Hole Diameter | | | 0.7 mm | (27.56 mils) |
| V-CUT Minimum Board Thickness | | | 0.6 mm | (24 mils) |

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